# 2SD1259, 2SD1259A

## Silicon NPN triple diffusion planar type

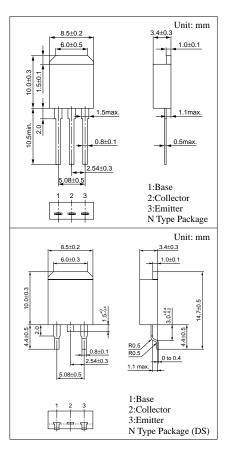
For power amplification with high forward current transfer ratio

#### Features

- High foward current transfer ratio h<sub>FE</sub>
- Satisfactory linearity of foward current transfer ratio h<sub>FE</sub>
- N type package enabling direct soldering of the radiating fin to the printed circuit board, etc. of small electronic equipment.

### Absolute Maximum Ratings (T<sub>C</sub>=25°C)

Parameter		Symbol	Ratings	Unit	
Collector to	2SD1259	3.7	80	V	
base voltage	2SD1259A	$V_{CBO}$	100		
Collector to	2SD1259	3.7	60	V	
emitter voltage	2SD1259A	$V_{CEO}$	80		
Emitter to base voltage		$V_{\mathrm{EBO}}$	6	V	
Peak collector current		$I_{CP}$	6	A	
Collector current		$I_{C}$	3	A	
Base current		$I_B$	1	A	
Collector power	T <sub>C</sub> =25°C	D	40	***	
dissipation	Ta=25°C	$P_{C}$	1.3	W	
Junction temperature		T <sub>j</sub>	150	°C	
Storage temperature		$T_{\rm stg}$	-55 to +150	°C	



#### Electrical Characteristics (T<sub>C</sub>=25°C)

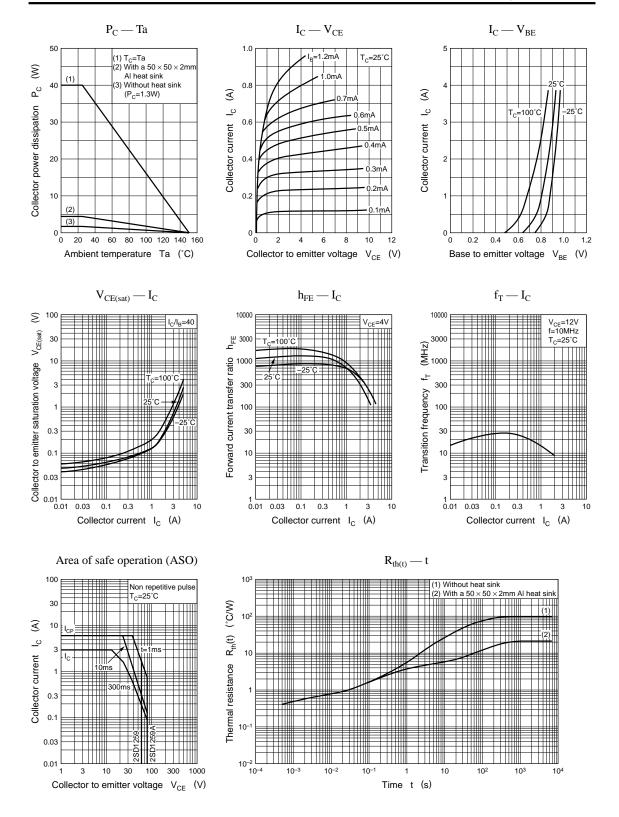
Parameter		Symbol	Conditions	min	typ	max	Unit	
Collector cutoff	2SD1259	т	$V_{CE} = 80V, I_{E} = 0$			100		
current	2SD1259A	1 <sub>CES</sub>	$V_{CE} = 100V, I_{E} = 0$			100	μΑ	
Collector cutoff current		I <sub>CEO</sub>	$V_{CE} = 40V, I_{B} = 0$			100	μΑ	
Emitter cutoff current		I <sub>EBO</sub>	$V_{CB} = 6V, I_C = 0$			100	μΑ	
Collector to emitter	2SD1259	17	$I_C = 25 \text{mA}, I_B = 0$	60			V	
voltage	2SD1259A	$V_{CEO}$		80				
Forward current transfer ratio		h <sub>FE</sub> *	$V_{CE} = 4V, I_{C} = 0.5A$	500		2500		
Collector to emitter saturation voltage		V <sub>CE(sat)</sub>	$I_C = 2A, I_B = 0.05A$			1	V	
Transition frequency		$f_T$	$V_{CE} = 12V, I_C = 0.2A, f = 10MHz$		50		MHz	

#### \*h<sub>FE</sub> Rank classification

Rank	Q	P	О	
$h_{FE}$	500 to 1000	800 to 1500	1200 to 2500	

Note: Ordering can be made by the common rank (PQ rank  $h_{FE} = 500$  to 1500) in the rank classification.

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